

### **General Description**

The 870931I-01 is an LVCMOS clock generator that uses an internal phase lock loop (PLL) for frequency multiplication and to lock the low-skew outputs to the reference clock. The device offers six outputs. The PLL loop filter is completely internal and does not require external components. Several combinations of the PLL feedback and a divide-by-2 (controlled by FREQ\_SEL) allow applications to optimize frequency generation over a wide range of input reference frequencies. The PLL can also be disabled by the PLL\_EN control signal to allow for low frequency or DC testing. The 870931I-01 device is a member of the family of high performance clock solutions from IDT.

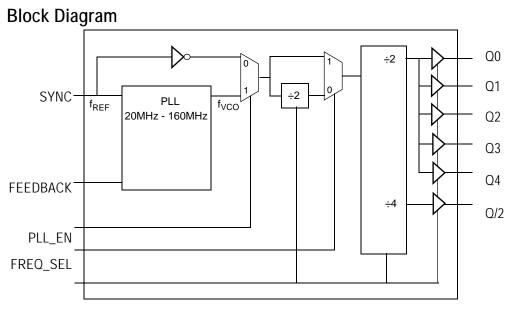
### Pin Assignment

GND □	1	20	□ Q4
OE/nRST □	2	19	□ Q/2
FEEDBACK 🗆	3	18	GND
AV <sub>DD</sub>	4	17	□ Q3
V <sub>DD</sub>	5	16	<b>□ V</b> DD
AGND □	6	15	□ Q2
SYNC□	7	14	GND
FREQ_SEL□	8	13	□ PLL_EN
GND□	9	12	GND
Q0 🗆	10	11	□ Q1

870931I-01 20-Lead QSOP, 150Mil 3.9mm x 8.65mm x 1.5mm package body R Package Top View

#### **Features**

- Single-ended input reference clock
- Six single-ended clock outputs
- Internal PLL does not require external loop filter components
- 5V tolerant inputs
- Maximum output frequency: 80MHz, (Q0:Q4 outputs)
- Maximum output frequency: 40MHz, (Q/2 output)
- LVCMOS interface levels for all inputs and outputs
- PLL disable feature for low-frequency testing
- Output drive capability: ±24mA
- Output skew: 300ps (maximum), Q0:Q4 and Q/2
- Full 3.3V supply voltage
- Available in lead-free packages
- -40°C to 85°C ambient operating temperature
- Fully pin and function compatible with the IDTQS5LV931 (including 50, 66 and 80MHz options)





# **Table 1. Pin Descriptions**

Number	Name	Туре	Description	
1, 9, 12, 14, 18	GND	Power	Power supply ground.	
2	OE/nRST	Input	Output enable and asynchronous reset. Resets all outputs. Logic LOW, the outputs are in high-impedance state. Logic HIGH enables all outputs. LVCMOS/LVTTL interface levels.	
3	FEEDBACK	Input	PLL feedback input which is connected to one of the clock outputs to close the PLL feedback loop. LVCMOS/LVTTL interface levels.	
4	$AV_DD$	Power	Positive power supply for the PLL.	
5, 16	$V_{DD}$	Power	Positive power supply pins.	
6	AGND	Power	Power supply ground for the PLL.	
7	SYNC	Input	Single-ended reference clock input. LVCMOS/LVTTL interface levels.	
8	FREQ_SEL	Input	Frequency select. Logic LOW level inserts a divide-by-2 into the PLL output and feedback path. Logic HIGH inserts a divide-by-1 into the PLL output and feedback path. LVCMOS/LVTTL interface levels.	
10, 11, 15, 17, 20	Q0, Q1, Q2, Q3, Q4	Output	Single-ended clock outputs. LVCMOS/LVTTL interface levels.	
13	PLL_EN	Input	PLL enable. Enable and disables the PLL. Logic HIGH enables the PLL. Logic LOW disables the PLL and the input reference signal is routed to the output dividers (PLL bypass). LVCMOS/LVTTL interface levels.	
19	Q/2	Output	Single-ended clock output. LVCMOS/LVTTL interface levels.	

# **Table 2. Pin Characteristics**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
C <sub>PD</sub>	Power Dissipation Capacitance	$V_{DD} = AV_{DD} = 3.6V$		330		pF
R <sub>OUT</sub>	Output Impedance			11		Ω



### **Device Configuration**

The 870931I-01 requires a connection to one of the clock outputs to the FEEDBACK input to close the PLL feedback path. The selection of the output (output divider) for PLL feedback will impact the device configuration and input to output frequency ratio and frequency ranges. See Table 3D for details.

## **Function Tables**

### Table 3A. OE/nRST Mode Configuration Table

Input	
OE/nRST	Operation
0	Device is reset and the outputs Q0:Q4 and Q/2 are in high-impedance state. This control is asynchronous.
1	Outputs are enabled.

### Table 3B. FREQ\_SEL Mode Configuration Table

Input	
FREQ_SEL	Operation
0	The VCO output is frequency-divided by 2. This setting allows for a lower input frequency range. See also table 3D for available frequency ranges.
1	The VCO output is frequency-divided by 1. This setting allows for a higher input frequency range. See also table 3D for available frequency ranges.

### Table 3C. PLL\_EN Mode Configuration Table

Input	
PLL_EN	Operation
0	The PLL is bypassed. The input reference clock is routed to the output dividers for low-frequency board test purpose. The PLL-related AC specifications do not apply in PLL bypass mode.
1	The PLL is enabled and locks to the input reference signal.

#### **Table 3D. Frequency Configuration Table**

Outputs Used for		Input Frequency Range (MHz)	Output Frequency Output-to-Input Frequen	
PLL Feedback	FREQ_SEL	SYNC	Q[0:4]	Q/2
Q0, Q1, Q2,	0	5 - 40	5 - 40 (1x)	2.5 - 20 (0.5x)
Q3 or Q4	1	10 - 80	10 - 80 (1x)	5 - 40 (0.5x)
Q/2	0	2.5 - 20	5 - 40 (2x)	2.5 - 20 (1x)
	1	5 - 40	10 - 80 (2x)	5 - 40 (1x)



## **Absolute Maximum Ratings**

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics or AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, V <sub>DD</sub>	4.6V
Inputs, V <sub>I</sub>	-0.5V to V <sub>DD</sub> + 0.5V
Outputs, V <sub>O</sub>	-0.5V to V <sub>DD</sub> + 0.5V
Package Thermal Impedance, $\theta_{JA}$	72.3°C/W (0 lfpm)
Storage Temperature, T <sub>STG</sub>	-65°C to 150°C

### **DC Electrical Characteristics**

### Table 4A. Power Supply DC Characteristics, $V_{DD}$ = AV $_{DD}$ = 3.3V $\pm$ 0.3V, $T_A$ = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD,} AV_{DD}$	Positive Supply Voltage		3.0	3.3	3.6	V
I <sub>DDQ</sub>	Quiescent Power Supply Current	$V_{DD} = AV_{DD} = Max., OE/nRST = 0,$ SYNC =0, All Outputs Open			5	mA

### Table 4B. LVCMOS/LVTTL DC Characteristics, $V_{DD}$ = AV $_{DD}$ = 3.3V $\pm$ 0.3V, $T_A$ = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage			2		V <sub>DD</sub> + 0.3	V
V <sub>IL</sub>	Input Low Voltage			-0.3		0.8	V
I <sub>IH</sub>	Input High Current	SYNC, OE/nRST, FEEDBACK, PLL_EN, FREQ_SEL	$V_{DD} = V_{IN} = 3.3V$			5	μΑ
I <sub>IL</sub>	Input Low Current	SYNC, OE/nRST, FEEDBACK, PLL_EN, FREQ_SEL	$V_{DD} = 3.3V, V_{IN} = 0V$	-5			μΑ
V <sub>OH</sub>	Output High Voltage:	Q0:Q4, Q/2	I <sub>OH</sub> = -24 mA	2.6			V
V <sub>OL</sub>	Output Low Voltage	Q0:Q4, Q/2	I <sub>OL</sub> = 24 mA			0.5	V
I <sub>OZ</sub>	Output Leakage Current	Q0:Q4, Q/2	$\begin{aligned} \text{OE/nRST} &= 0, \\ \text{V}_{\text{OUT}} &= \text{OV or V}_{\text{DD}}, \\ \text{V}_{\text{DD}} &= 3.6 \text{V} \end{aligned}$			±5	μΑ



Table 5. AC Electrical Characteristics,  $V_{DD}$  = AV $_{DD}$  = 3.3V  $\pm$  0.3V,  $T_A$  = -40°C to 85°C

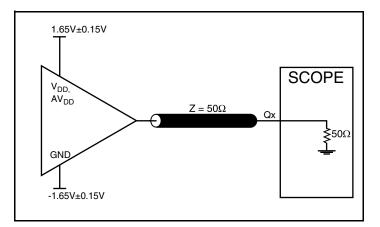
Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
			Feedback of Q0:Q4, FREQ_SEL = 0	5		40	MHz
4	SYNC Input Reference		Feedback of Q0:Q4, FREQ_SEL = 1	10		80	MHz
f <sub>REF</sub>	Frequency		Feedback of Q/2, FREQ_SEL = 0	2.5		20	MHz
			Feedback of Q/2, FREQ_SEL = 1	5		40	MHz
4	Output Frequency		Q0-Q4			80	MHz
f <sub>OUT</sub>	Output Frequency		Q/2			40	MHz
idc	Input Duty Cycle		SYNC	25		75	%
$t_R / t_F$	Input Rise/ Fall Tim	ne	SYNC			3	ns
tsk(o)	Output Skew; NOT	E 1, 2, 3	Rising edges of Q0:Q4 and Q/2			300	ps
isk(U)	Output Skew; NOT	E 1, 2, 3	Falling edges of Q0:Q4			300	ps
+	Output		80MHz	t <sub>PERIOD</sub> /2 - 0.5		t <sub>PERIOD</sub> /2 + 0.5	ns
t <sub>PW</sub>	Pulse Width	Q/2	40MHz	t <sub>PERIOD</sub> /2 - 0.4		t <sub>PERIOD</sub> /2 + 0.4	ns
tjit(cc)	Cycle-to-Cycle Jitter		Feedback = Q			320	ps
ijii(CC)	Cycle-to-Cycle ditte	71	Feedback = Q/2			530	ps
t(\$)	Static Phase Offset, (SYNC to FEEDBACK delay); NOTE 2, 4	Q0:Q4	80MHz	-500		500	ps
t <sub>PZL</sub>	Output Enable Time; NOTE 5	OE/nRST	Low-to-High			14	ns
t <sub>PHZ,</sub> t <sub>PLZ</sub>	Output Disable Time; NOTE 5	OE/nRST	High-to-Low			14	ns
t <sub>R</sub> / t <sub>F</sub>	Output Rise/ Fall Time	Q0:Q4, Q/2	0.8V - 2.0V	0.2		2	ns
t <sub>LOCK</sub>	PLL Lock Time					10	ms

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

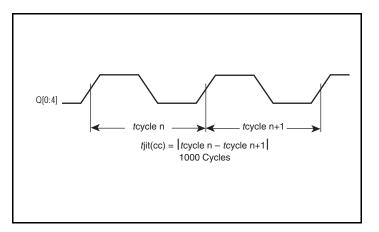
- NOTE 1: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V<sub>DD</sub>/2.
- NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.
- NOTE 3: Measured between coincident rising output edges of Q0:Q4 and Q/2.
- NOTE 4: Defined as the time difference between the input reference clock and the average feedback input signal when the PLL is locked and the input reference frequency is stable.
- NOTE 5: These parameters are guaranteed by characterization. Not tested in production.



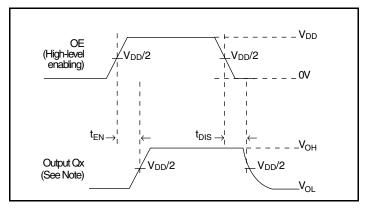
## **Parameter Measurement Information**



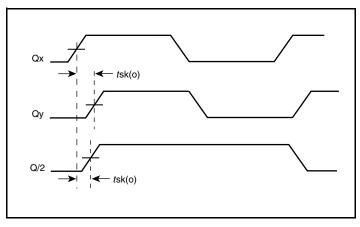
#### 3.3V Output Load AC Test Circuit



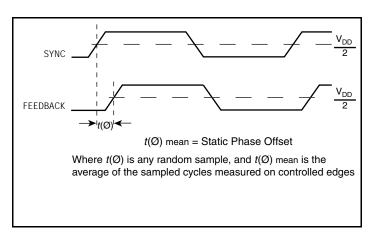
Cycle-to-Cycle Jitter



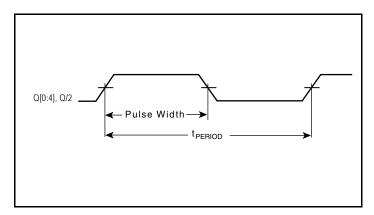
**Output Enable/Disable** 



**Output Skew** 



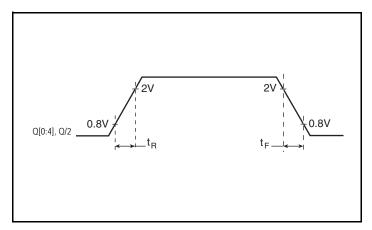
**Static Phase Offset** 



**Output Pulse Width** 



## **Parameter Measurement Information, continued**



**Output Rise/Fall Time** 

# **Application Information**

## **Recommendations for Unused Output Pins**

### **Outputs:**

### **LVCMOS Outputs**

All unused LVCMOS output can be left floating. There should be no trace attached.



### **Schematic Example**

Figure 1 shows an example of an 870931I-01 application schematic. In this example, the device is operated at  $V_{DD} = 3.3V$ . The decoupling capacitors should be located as close as possible to the

power pin. The input is driven by a 3.3V LVCMOS driver. An example of LVCMOS termination is shown in this schematic.

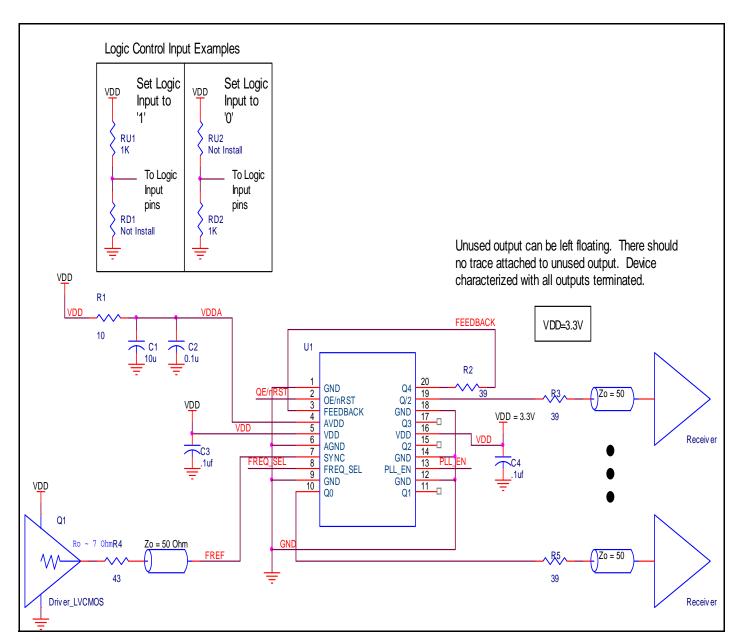


Figure 1. 870931I-01 Schematic Layout Example



#### **Power Considerations**

This section provides information on power dissipation and junction temperature for the 870931I-01. Equations and example calculations are also provided.

#### 1. Power Dissipation.

The total power dissipation for the 870931I-01 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for  $V_{DD} = 3.3V + 0.3V = 3.6V$ , which gives worst case results.

- Power (core)<sub>MAX</sub> =  $V_{DD\ MAX}$  \*  $I_{DD\ MAX}$  = 3.6V \*5mA = **18mW**
- Output Impedance  $R_{OUT}$  Power Dissipation due to Loading  $50\Omega$  to  $V_{DD}/2$  Output Current  $I_{OUT} = V_{DD\ MAX}$  /  $[2*(50\Omega + R_{OUT})] = 3.6V$  /  $[2*(50\Omega + 11\Omega)] =$  **29.5mA**
- Power Dissipation on the R<sub>OUT</sub> per LVCMOS output Power (R<sub>OUT</sub>) = R<sub>OUT</sub> \* (I<sub>OUT</sub>)<sup>2</sup> = 11 $\Omega$  \* (29.5mA)<sup>2</sup> = **9.57mW per output**
- Total Power (R<sub>OUT</sub>) = R<sub>OUT</sub> (per output) \* number of outputs = 9.57mW \* 6 outputs = 57.42mW

#### **Dynamic Power Dissipation at 80MHz**

Power (80MHz) = 
$$C_{PD}$$
 \* Frequency \*  $(V_{DD})^2$  = 330pF \* 80MHz \*  $(3.6V)^2$  = **342mW**

#### **Total Power**

- = Power (core)<sub>MAX</sub> + Total Power ( $R_{OUT}$ ) + Power (80MHz)
- = 18mW + 57.42mW + 342mW
- = 417.42mW

#### 2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS devices is 125°C.

The equation for Tj is as follows: Tj =  $\theta_{JA}$  \* Pd\_total + T<sub>A</sub>

Tj = Junction Temperature

 $\theta_{JA}$  = Junction-to-Ambient Thermal Resistance

Pd\_total = Total Device Power Dissipation (example calculation is in section 1 above)

T<sub>A</sub> = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming no air flow and a multi-layer board, the appropriate value is 72.3°C/W per Table 6 below.

Therefore, Tj for an ambient temperature of 85°C with all outputs switching is:

 $85^{\circ}\text{C} + 0.417\text{W} * 72.3^{\circ}\text{C/W} = 115.1^{\circ}\text{C}$ . This is well below the limit of  $125^{\circ}\text{C}$ .

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

### Table 6. Thermal Resistance $\theta_{\text{JA}}$ for a 20 Lead QSOP, Forced Convection

$\theta_{JA}$ by Velocity						
Linear Feet per Minute	0	200	500			
Multi-Layer PCB, JEDEC Standard Test Boards	72.3°C/W	64.4°C/W	61.0°C/W			



## **Reliability Information**

Table 7.  $\theta_{\text{JA}}$  vs. Air Flow Table for a 20 Lead QSOP

$ heta_{JA}$ vs. Air Flow						
Linear Feet per Minute	0	200	500			
Multi-Layer PCB, JEDEC Standard Test Boards	72.3°C/W	64.4°C/W	61.0°C/W			

#### **Transistor Count**

The transistor count for 870931I-01: 1489

## **Package Outline and Package Dimensions**

Package Outline - R Suffix for 20 Lead QSOP, 150MIL

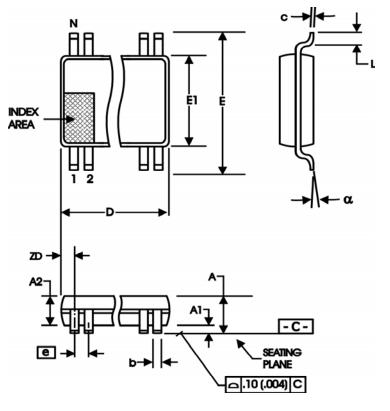


Table 8. Package Dimensions for 20 Lead QSOP

All Dimensions in Millimeters				
Symbol	Minimum	Maximum		
N	20			
Α	1.35	1.75		
A1	0.10	0.25		
A2		1.50		
b	0.20	0.30		
С	0.18	0.25		
D	8.55	8.750		
E	5.80	6.20		
E1	3.80	4.00		
е	0.635 Basic			
L	0.40	1.27		
α	0°	8°		
ZD	1.47 Ref			

Reference Document: JEDEC Publication 95, MO-137



# **Ordering Information**

## **Table 9. Ordering Information**

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
870931ARI-01LF	870931AI01L	"Lead-Free" 20 Lead QSOP	Tube	-40°C to 85°C
870931ARI-01LFT	870931AI01L	"Lead-Free" 20 Lead QSOP	Tape & Reel	-40°C to 85°C



# **Revision History Sheet**

Rev	Table	Page	Description of Change	Date
Α		8	Added Layout Schematic.	6/10/09
Α	Т9	11	Removed leaded orderable parts from the Ordering Information table	11/15/12
Α	Т9	1 11	Removed ICS from part number were needed.  General Description - Deleted ICS Chip and HiperClocks.  Ordering Information - Deleted LF note below table. Removed quantity for tape and reel.  Updated header and footer.	1/27/16
В		1	Corrected header title.	4/25/16



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ZL30245LFG7 PI6LC48P0405LIE PI6LC48P03LE MAX24505EXG+ ZL30163GDG2 5L1503L-000NVGI8 ZL30156GGG2 ZL30673LFG7
MAX24188ETK2 ZL30152GGG2 5L1503-000NVGI8 PI6C557-01BZHIEX PI6LC48C21LIE CY2542QC002 5P35023-106NLGI
5X1503L-000NLGI8 ZL30121GGG2V2 ZL30282LDG1 ZL30102QDG1 ZL30159GGG2 DS1070K ZL30145GGG2 ZL30312GKG2
MAX24405EXG2 ZL30237GGG2 SY100EL34LZG 9FGV1002BQ506LTGI AD9518-4ABCPZ MX852BB0030 PI6LC4840ZHE AD95160BCPZ-REEL7 AD9574BCPZ-REEL7 PL602-21TC-R ZL30105QDG1 ZL30100QDG1